

General Description

This Power MOSFET is produced using Cmos's advanced planar stripe DMOS technology. This advanced technology has been especially tailored to minimize on-state resistance, provide superior switching performance, and withstand high energy pulse in the avalanche and commutation mode. These devices are well suited for high efficiency switched mode power supplies, active power factor correction based on half bridge topology

Features

- $R_{DS(ON)} < 4\Omega$ @ $V_{GS} = 10V$
- 100% avalanche tested
- RoHS Compliant
- Low gate charge
- Improved dv/dt capability

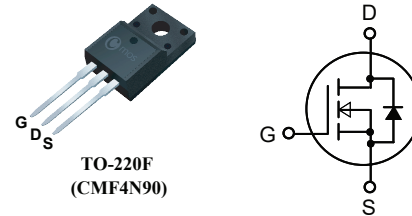
Product Summary

BVDSS	RDSON	ID
900V	4Ω	4A

Applications

- Switching application
- Switch mode power supply (SMPS)
- AC adaptors

TO-220F Pin Configuration



Absolute Maximum Ratings (Tc=25°C unless otherwise noted)

Symbol	Parameter	Rating	Units
V_{DSS}	Drain-Source Voltage	900	V
I_D	Drain Current - Continuous ($T_C = 25^\circ C$) - Continuous ($T_C = 100^\circ C$)	4	A
		2.5	A
I_{DM}	Drain Current - Pulsed	12	A
V_{GSS}	Gate-Source Voltage	± 30	V
E_{AS}	Single Pulsed Avalanche Energy ¹	70	mJ
P_D	Power Dissipation ($T_C = 25^\circ C$)	50	W
T_J, T_{STG}	Operating and Storage Temperature Range	-55 to +150	°C

Thermal Characteristics

Symbol	Parameter	Rating	Units
$R_{\theta JC}$	Thermal Resistance, Junction-to-Case	3.3	°C/W
$R_{\theta JA}$	Thermal Resistance, Junction-to-Ambient	65	°C/W

Electrical Characteristic (T_c=25°C unless otherwise noted)

Symbol	Parameter	Test Conditions	Min	Typ	Max	Units
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Off Characteristics

BV _{DSS}	Drain-Source Breakdown Voltage	V _{GS} = 0 V, I _D = 250 μA	900	--	--	V
I _{DSS}	Zero Gate Voltage Drain Current	V _{DS} = 900 V, V _{GS} = 0 V	--	--	1	μA
		V _{GS} = 720V, T _C = 125°C	--	--	100	nA
I _{GSSF}	Gate-Body Leakage Current, Forward	V _{GS} = 30 V, V _{DS} = 0 V	--	--	100	nA
I _{GSSR}	Gate-Body Leakage Current, Reverse	V _{GS} = -30 V, V _{DS} = 0 V	--	--	-100	nA

On Characteristics

V _{GS(th)}	Gate Threshold Voltage	V _{DS} = V _{GS} , I _D = 250 μA	3	--	5	V
R _{DS(on)}	Static Drain-Source on-Resistance	V _{GS} = 10 V, I _D = 2A	--	3.6	4	Ω
g _{FS}	Forward Transconductance	V _{DS} = 10V, I _D = 2A	--	4	--	S
R _g	Gate Resistance	V _{DS} =0V, V _{GS} =0V, f=1MHz	--	2.3	--	Ω

Dynamic Characteristics

C _{iss}	Input Capacitance	V _{DS} = 25V, V _{GS} = 0 V f = 1.0 MHz	--	800	--	pF
C _{oss}	Output Capacitance		--	50	--	pF
C _{rss}	Reverse Transfer Capacitance		--	5.5	--	pF

Switching Characteristics

t _{d(on)}	Turn-On Delay Time	V _{DS} = 450 V, I _D = 4A R _G = 25Ω, V _{GS} = 10V	--	22	--	ns
t _r	Turn-On Rise Time		--	45	--	ns
t _{d(off)}	Turn-Off Delay Time		--	43	--	ns
t _f	Turn-Off Fall Time		--	40	--	ns
Q _g	Total Gate Charge	V _{DS} = 720 V, I _D = 4A V _{GS} = 10 V	--	18.5	--	nC
Q _{gs}	Gate-Source Charge		--	4.5	--	nC
Q _{gd}	Gate-Drain Charge		--	8	--	nC

Drain-Source Diode Characteristics and Maximum Ratings

I _S	Maximum Continuous Drain-Source Diode Forward Current	--	--	4	A	
I _{SM}	Maximum Pulsed Drain-Source Diode Forward Current	--	--	12	A	
V _{SD}	Drain-Source Diode Forward Voltage	V _{GS} = 0 V, I _S = 4A	--	--	1.2	V
t _{rr}	Reverse Recovery Time	I _F = 4A, T _J = 25°C, V _{DS} = 100V dI _F / dt = 100 A/μs	--	196	--	ns
Q _{rr}	Reverse Recovery Charge		--	4.05	--	μC

Note:

1. L=5mH, I_{AS}=5.5A, V_{DD}=100V, R_G=25Ω, Starting T_J=25°C

This product has been designed and qualified for the consumer market.

Cmos assumes no liability for customers' product design or applications.

Cmos reserves the right to improve product design, functions and reliability without notice.

Typical Characteristics

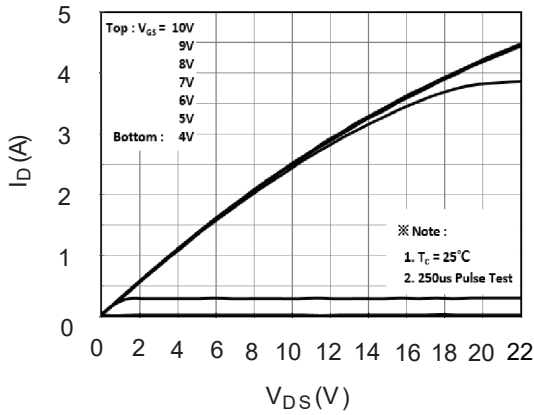


Fig. 1 Typical Output Characteristics

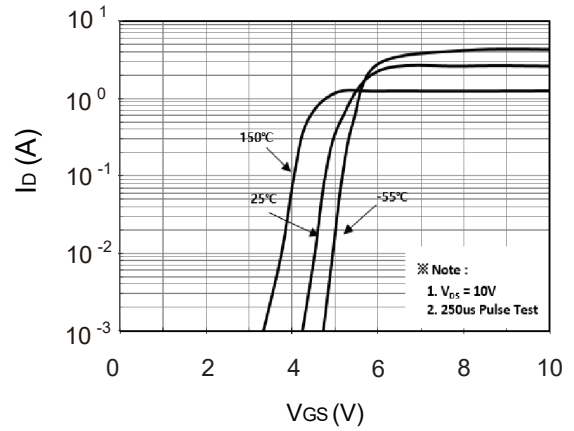


Fig. 2 Typical Transfer Characteristics

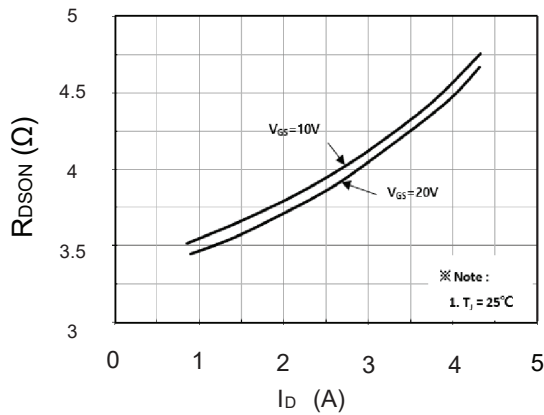


Fig.3 On-Resistance Variation with Drain Current and Gate Voltage

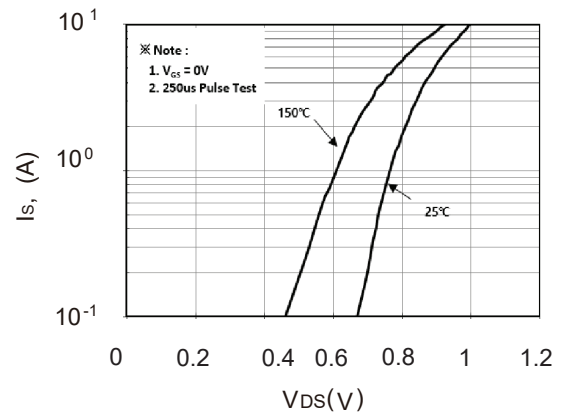


Fig. 4 Body Diode Forward Voltage Variation with Source Current

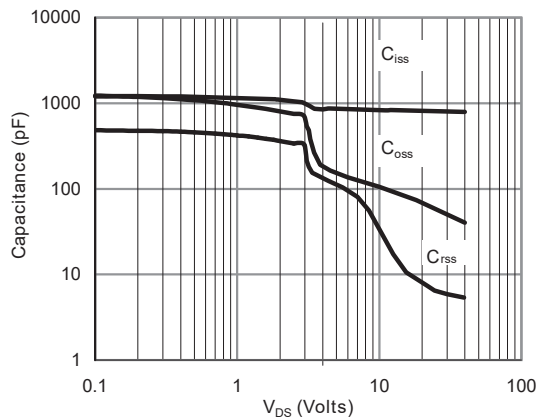


Fig. 5 Typical Capacitance Characteristics

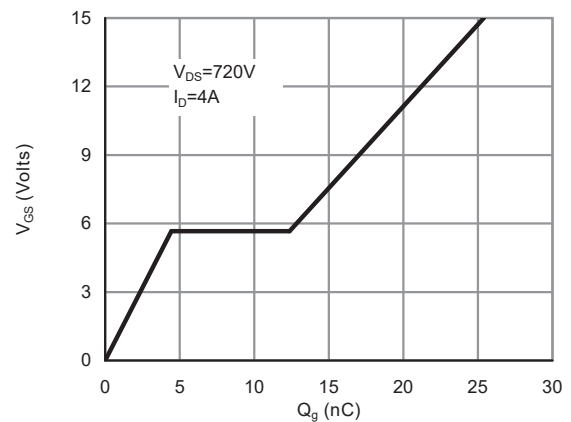


Fig. 6 Typical Total Gate Charge Characteristics

Typical Characteristics

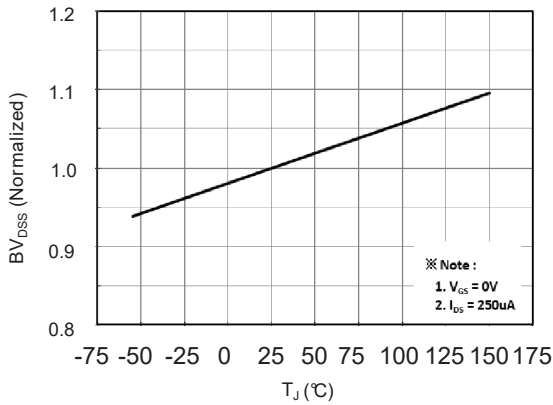


Fig. 7 Breakdown Voltage Variation vs. Temperature

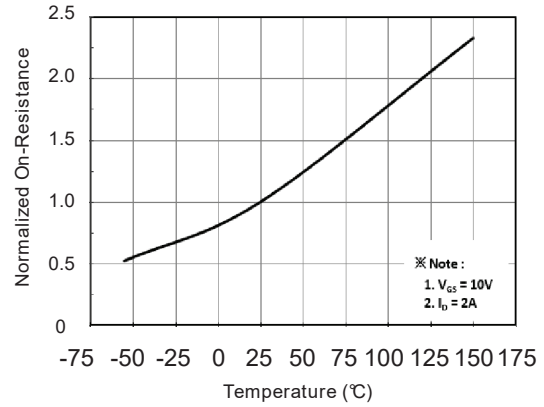


Fig. 8 On-Resistance Variation vs. Temperature

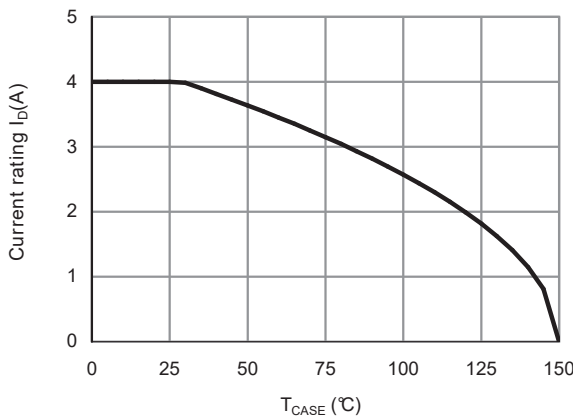


Figure 9: Current De-rating (Note B)

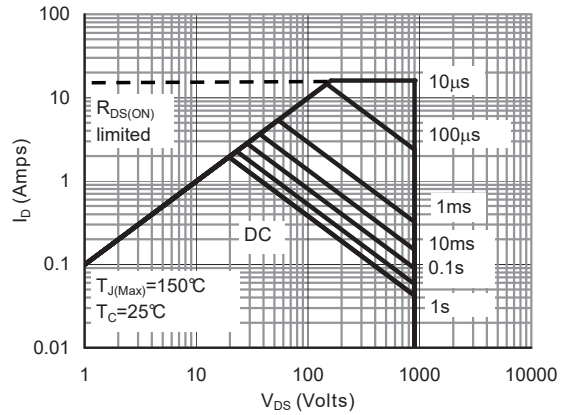


Figure 10: Maximum Forward Biased Safe Operating Area for AOTF4N90 (Note F)

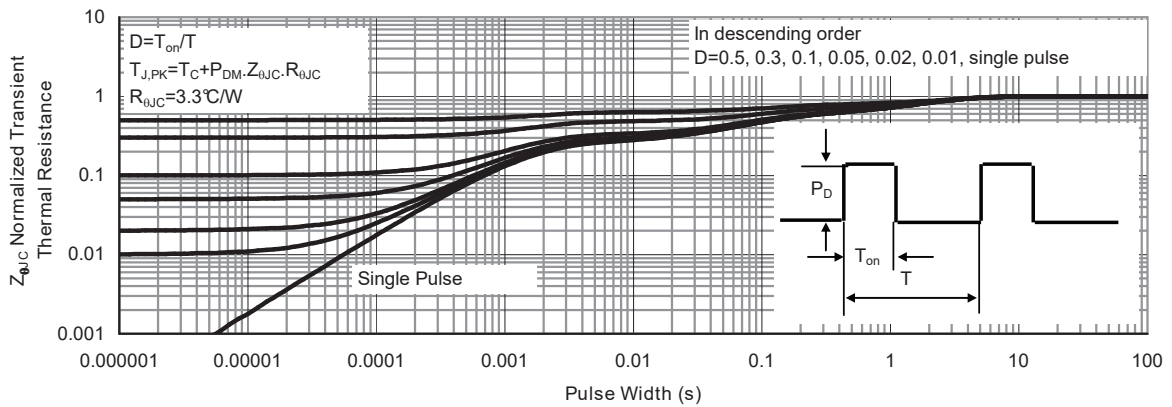


Figure 11: Normalized Maximum Transient Thermal Impedance for AOTF4N90 (Note F)